

NOTES (UNLESS OTHERWISE SPECIFIED):

GENERAL

- 1) PCB IS 8-LAYER, .062" THICK.
- 2) CONSTRUCTION IS SOLDER-MASK-OVER-BARE-COPPER (SMOBC).
- 3) ACCEPTABILITY SHALL BE BASED ON IPC-A-600, CLASS 2.
- 4) THE FOLLOWING GERBER RS274X PHOTO TOOL FILES SHALL BE USED TO DEFINE ALL CIRCUIT FEATURES:

\*GTL - TOP LAYER GERBER DATA  
\*G1 - MID LAYER 1 GERBER DATA  
\*GP1- INTERNAL PLANE LAYER 1 GERBER DATA  
\*GP2 - INTERNAL PLANE LAYER 2 GERBER DATA  
\*GP3- INTERNAL PLANE LAYER 3 GERBER DATA  
\*GP4 - INTERNAL PLANE LAYER 4 GERBER DATA  
\*GP5 - INTERNAL PLANE LAYER 5 GERBER DATA  
\*GBL - BOTTOM LAYER GERBER DATA  
\*GBO BOTTOM OVERLAY GERBER DATA  
\*GBP - BOTTOM-SIDE SOLDER PASTE MASK  
\*GBS - BOTTOM SOLDER MASK GERBER DATA  
\*GTO - TOP OVERLAY GERBER DATA  
\*GTP - TOP-SIDE SOLDER PASTE MASK  
\*GTS - TOP SOLDER MASK GERBER DATA

- 5) THE PHOTO TOOL SHALL NOT BE COMPENSATED WITHOUT PRIOR ENGINEERING APPROVAL.  
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FABRICATION TOLERANCES

- 6) END PRODUCT CONDUCTOR WIDTHS AND PAD DIAMETERS SHALL NOT VARY MORE THAN 0.002" FROM THE 1:1 DIMENSIONS OF THE MASTER ARTWORK.
- 7) THE CONDUCTIVE PATTERN SHALL BE POSITIONED SO THAT THE LOCATION OF ANY PAD OR LAND SHALL BE WITHIN 0.005" DIAMETER TO THE TRUE POSITION OF THE HOLE IT CIRCUMSCRIBES.
- 8) ALL DRILL HOLE SIZES AND TOLERANCES APPLY AFTER PLATING.
- 9) THE MINIMUM ANNULAR RING SHALL BE 0.005".
- 10) BOW AND TWIST SHALL NOT EXCEED 0.010" PER INCH.
- 11) FOR PCB ROUTING DIMENSIONS: .XXX = +/- .005" .XX = +/- .020"

MATERIAL

- 12) BASE MATERIAL IS FR4 EPOXY FIBERGLASS
- 13) SEE STACK-UP LEGEND FOR COPPER CLADDING CALL OUTS

PLATING

- 14) ALL HOLES AND CONDUCTIVE SURFACES SHALL BE PLATED WITH A MINIMUM OF 0.001" COPPER.
- 15) AFTER SOLDERMASK, ALL EXPOSED HOLES AND CONDUCTIVE SURFACES SHALL BE COATED WITH A GOLD IMMERSION PLATING TO PRESERVE SOLDERABILITY.

COATINGS

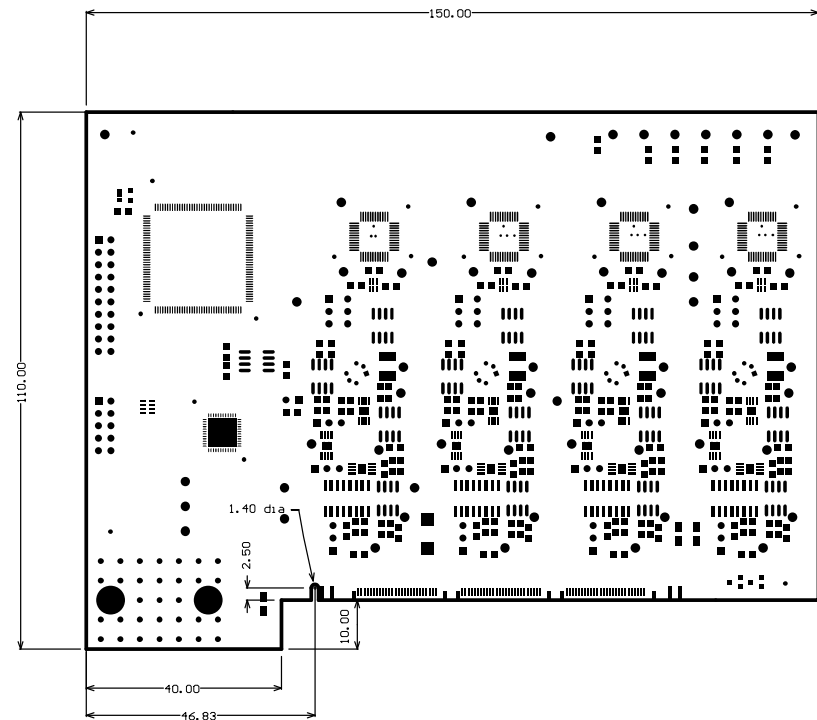
- 16) THE SOLDERMASK SHALL BE BLACK LIQUID PHOTO-IMAGEABLE PER IPC-SM-840, TYPE-B, CLASS 2.
- 17) THE SOLDERMASK REGISTRATION ALLOWANCE IS 0.003". THERE SHALL BE NO SOLDERMASK ON ANY SOLDER PAD OR LAND.

MARKING

- 18) THE LEGEND SHALL BE SCREEN-PRINTED USING PERMANENT YELLOW EPOXY INK.
- 19) THE SCREEN PRINTING REGISTRATION ALLOWANCE IS 0.007". THERE SHALL BE NO INK ON ANY SOLDER PAD OR LAND.
- 20) THE VENDOR CODE AND UL FLAMMABILITY RATING MAY BE ETCHED IN THE FOIL OR MARKED IN PERMANENT EPOXY INK (VENDOR'S OPTION).

ELECTRICAL TESTING

- 21) ALL BOARDS SHALL BE ELECTRICALLY TESTED TO THE SUPPLIED IPC-D-356A NET LIST FOR CONTINUITY, OPENS AND SHORTS.



Layer Stack Up Detail for: Sinistro_ASP_RevA.PcbDoc	
Layer Name	Copper cladding
Top Layer (.GTL)	1/2 oz (1 oz finished)
MidLayer1 (.G1)	1/2 oz
+28V and VCC (.GP1)	1/2 oz
A and D grounds (.GP2)	2 oz
Earth GND (.GP3)	2 oz
+5ANA (.GP4)	1/2 oz
-5ANA (.GP5)	1/2 oz
Bottom Layer (.GBL)	1/2 oz (1 oz finished)

**NOTICE**  
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PRIMARY PCB SPECIFICATIONS	
(REFER TO COMPLETE SPEC LISTING AT LEFT FOR FURTHER DETAILS)	
NUMBER OF LAYERS	8
FINISHED THICKNESS	.062"
BASE MATERIAL	FR4
PLATING TYPE	GOLD IMMERSION
SOLDER MASK COLOR	BLACK

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DATE 12/20/2012	DESIGNED Rich Lobdill	DRAWN Rich Lobdill	SCALE 1 : 1
CHECKED/DATE		APPROVED/DATE	
TITLE 175-00003, PCB, SINISTRO ASP BOARD			
REV C	DOC NO. - GPT		REV 2 SHEET 1 OF 14